

Slater & Matsil, L.L.P.

Suite 1000
17950 Preston Road
Dallas, Texas 75252-5793
Phone: 972-732-1001 Facsimile: 972-732-9218

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To Examiner: Shrinivas H. Rao	Total Pages Sent: 9
Technology Center 2800	(including cover sheet)
Facsimile Number: (571) 273-8300	Transmission Date: November 8, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

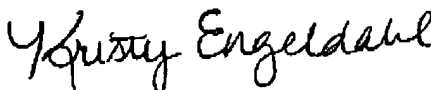
Applicant: Tews, *et al.* Docket No.: 2004 P 51343 US
Serial No.: 10/840,146 Art Unit: 2814
Date Filed: May 6, 2004
TITLE: Semiconductor Structures And Manufacturing Methods

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- Amendment (8 pages)

Respectfully submitted,



Kristy Engeldahl
Legal Assistant

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Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

The following amendments and remarks are presented in response to the Examiner's Office Action mailed September 27, 2005. Please amend the above-referenced application as follows.

2004 P 51343 US

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